

# Global 3D IC and 2.5D IC Packaging Market Research Report 2016

https://marketpublishers.com/r/GBECE71ECBCEN.html

Date: January 2017

Pages: 104

Price: US\$ 2,900.00 (Single User License)

ID: GBECE71ECBCEN

#### **Abstracts**

#### Notes:

Production, means the output of 3D IC and 2.5D IC Packaging

Revenue, means the sales value of 3D IC and 2.5D IC Packaging

This report studies 3D IC and 2.5D IC Packaging in Global market, especially in North America, Europe, China, Japan, Korea and Taiwan, focuses on top manufacturers in global market, with production, price, revenue and market share for each manufacturer, covering

Taiwan Semiconductor

Samsung Electronics

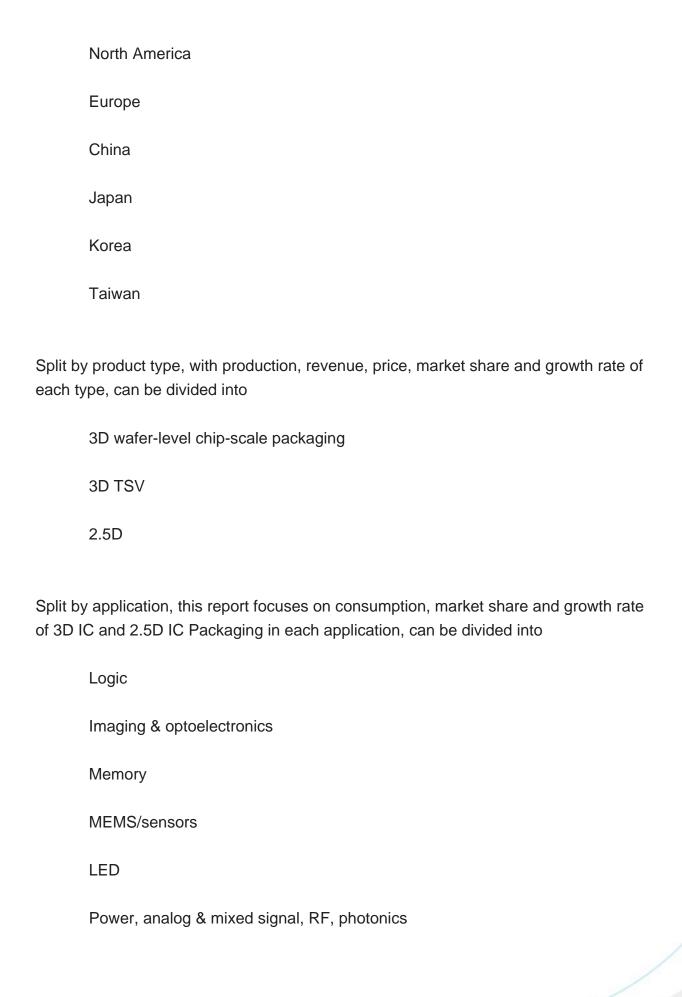
Toshiba Corp

Advanced Semiconductor Engineering

Amkor Technology

Market Segment by Regions, this report splits Global into several key Regions, with production, consumption, revenue, market share and growth rate of 3D IC and 2.5D IC Packaging in these regions, from 2011 to 2021 (forecast), like







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